

#### Features

- Ultra Low  $V_F$  per Footprint Area
- Low Thermal Resistance
- One-fifth Footprint of SMA
- Super Low Profile (<.8mm)
- Available Tested on Tape & Reel



#### Major Ratings and Characteristics

Characteristics	IR130CPS	Units
$I_{F(AV)}$ Rectangular waveform	1.0	A
$V_{RRM}$	30	V
$I_{FSM}$ @tp = 5 $\mu$ s sine	220	A
$V_F$ @1.0 Apk, $T_J=125^\circ\text{C}$	0.33	V
$T_J$ range	-55 to 150	$^\circ\text{C}$

#### Description

True chip-scale packaging is available from International Rectifier. The IR130CPS surface-mount Schottky rectifier has been designed for applications requiring low forward drop and very small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, free-wheeling diodes, battery charging, and reverse battery protection.

- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability

The Flipky™ package, is one-fifth the footprint of a comparable SMA package and has a profile of less than .8mm. Combined with the low thermal resistance of the die level device, this makes the Flipky™ the best device for application where printed circuit board space is at a premium and in extremely thin application environments such as battery packs, cell phones and PCMCIA cards.

## Voltage Ratings

Part number	IR130CSP
V <sub>R</sub> Max. DC Reverse Voltage (V)	30
V <sub>RWM</sub> Max. Working Peak Reverse Voltage (V)	

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## Absolute Maximum Ratings

Parameters	Value	Units	Conditions
I <sub>F(AV)</sub> Max. Average Forward Current	1.0	A	50% duty cycle @ T <sub>PCB</sub> = 120 °C, rectangular wave form
I <sub>FSM</sub> Max. Peak One Cycle Non-Repetitive Surge Current @ 25 °C	220	A	Following any rated load condition and with rated V <sub>RRM</sub> applied
	21		
E <sub>AS</sub> Non- Repetitive Avalanche Energy	10	mJ	T <sub>J</sub> = 25 °C, I <sub>AS</sub> = 2.0A, L = 5.0mH
I <sub>AR</sub> Repetitive Avalanche Current	2.0	A	Current decaying linearly to zero in 1 µsec Frequency limited by T <sub>J</sub> max. Va = 1.5 x Vr typical

## Electrical Specifications

Parameters	Typ.	Max.	Units	Conditions
V <sub>FM</sub> Max. Forward Voltage (1) Drop	0.41	0.45	V	@ 1A
	0.46	0.50		@ 2A
	0.29	0.33		@ 1A
	0.37	0.40		@ 2A
I <sub>RM</sub> Max. Reverse Leakage (1) Current	30	100	µA	T <sub>J</sub> = 25 °C
	10	30	mA	T <sub>J</sub> = 125 °C
C <sub>T</sub> Max. Junction Capacitance	-	210	pF	V <sub>R</sub> = 5V <sub>DC</sub> (test signal range 100kHz to 1MHz) 25 °C
dv/dt Max. Volatge Rate of Charge	-	10000	V/ µs	(Rated V <sub>R</sub> )

(1) Pulse Width &lt; 300µs, Duty Cycle &lt; 2%

## Thermal-Mechanical Specifications

Parameters	Value	Units	Conditions
T <sub>J</sub> Max. Junction Temperature Range (*)	-55 to 150	°C	
T <sub>stg</sub> Max. Storage Temperature Range	-55 to 150	°C	
R <sub>thJL</sub> Typ. Thermal Resistance Junction to PCB (**)	40	°C/W	DC operation
R <sub>thJA</sub> Max. Thermal Resistance Junction to Ambient	62	°C/W	

(\*)  $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

(\*\*) Mounted 1 inch square PCB

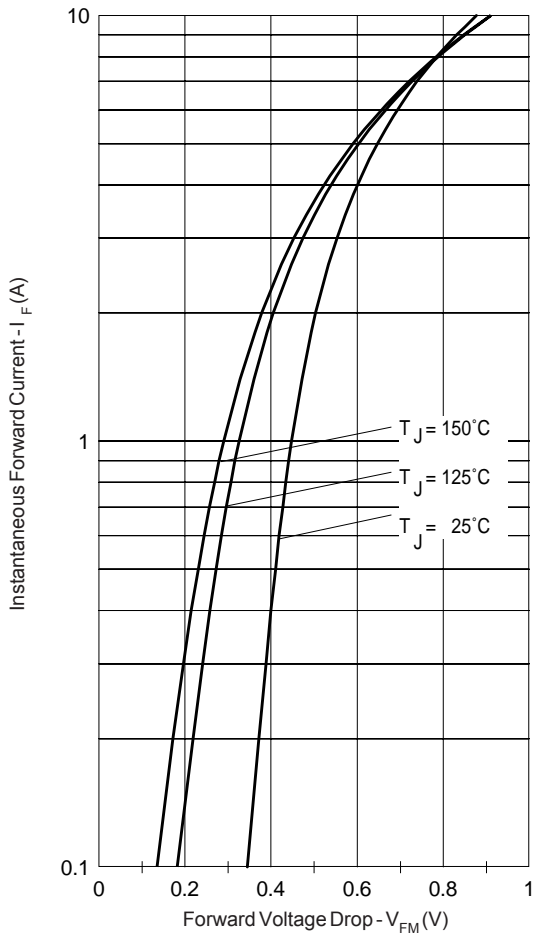


Fig. 1 - Max. Forward Voltage Drop Characteristics (Per Leg)

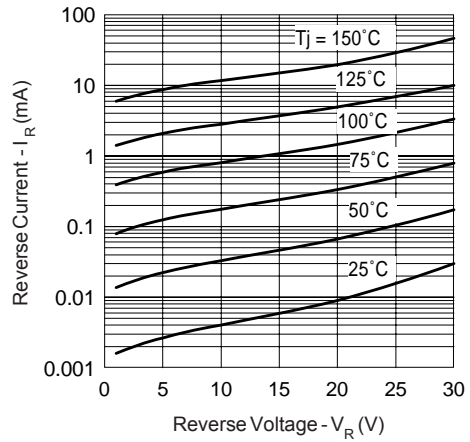


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage (Per Leg)

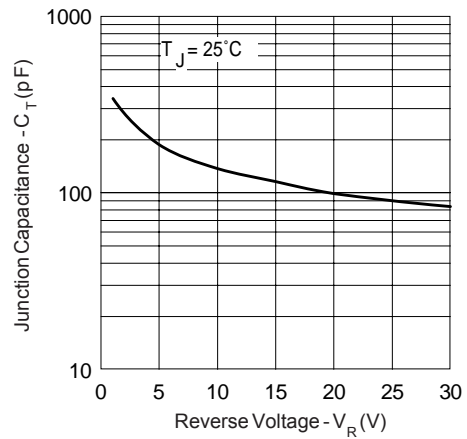


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage (Per Leg)

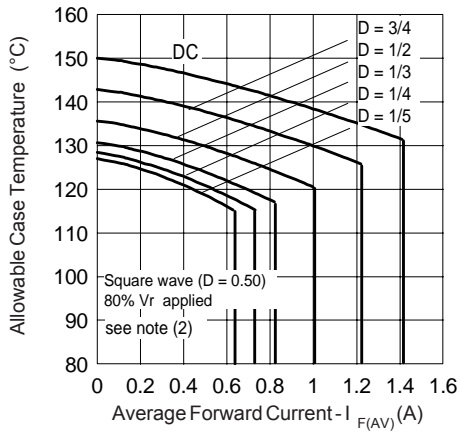


Fig. 4 - Max. Allowable Case Temperature Vs. Average Forward Current (Per Leg)

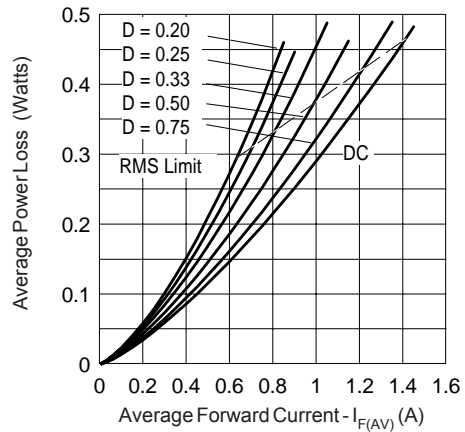


Fig. 5 - Forward Power Loss Characteristics (Per Leg)

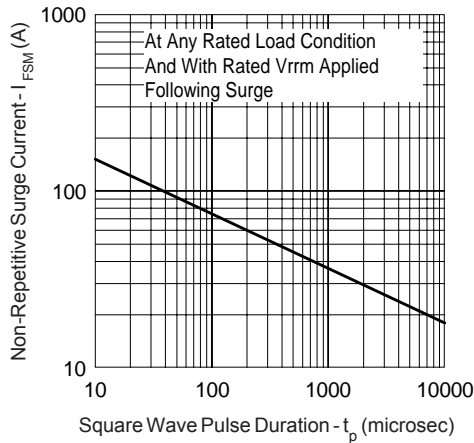


Fig. 6 - Max. Non-Repitative Surge Current (Per Leg)

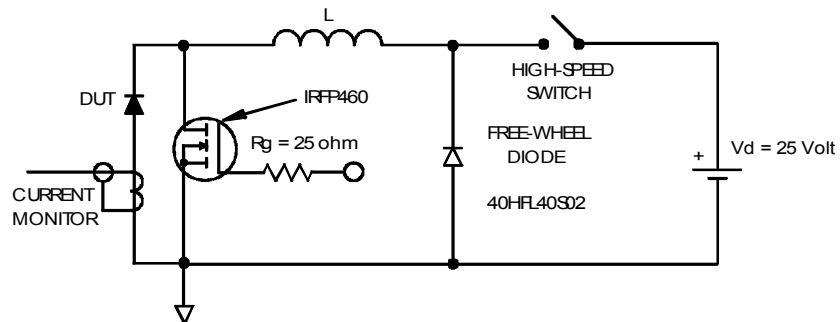
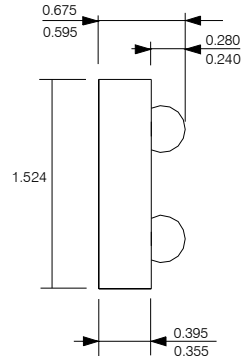
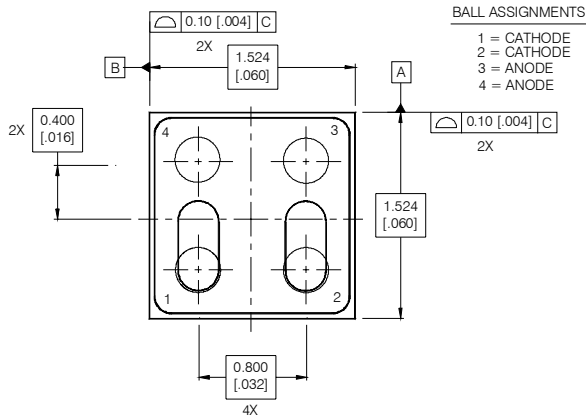


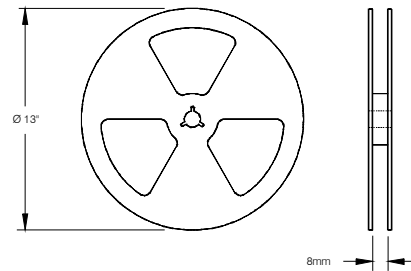
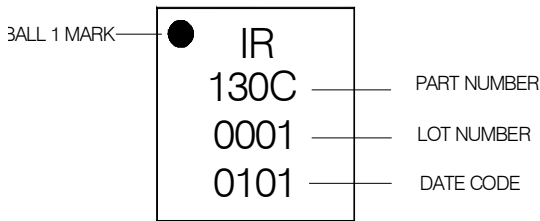
Fig. 8 - Unclamped Inductive Test Circuit

- (2) Formula used:  $T_c = T_j - (Pd + Pd_{REV}) \times R_{thJC}$ ;  
 $Pd = \text{Forward Power Loss} = I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$  (see Fig. 6);  
 $Pd_{REV} = \text{Inverse Power Loss} = V_{R1} \times I_R (1 - D); I_R @ 80\% V_R \text{ applied}$

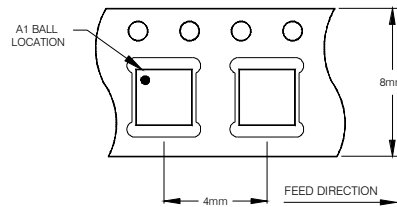
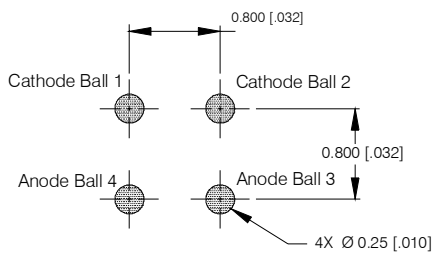
FlipKY™ Outline Dimension and Tape and Reel



NOTES:  
 1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.  
 2. CONTROLLING DIMENSION: MILLIMETER  
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].



RECOMMENDED FOOTPRINT



NOTES:  
 1. TAPE AND REEL OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.  
 This product has been designed for Consumer Level.  
 Qualification Standards can be found on IR's Web site.